Automotive Cluster Telltale Driver Reference Design - TIDA-00278

Solution Features

- Low and accurate Rdson for the internal MOSFET
- Slow switching time: rise time=207ns fall time=128ns
- Thermal shutdown protection
- The entire cluster solution supports 4.5V-40V system capabilities

Solution Benefits

- Allowing low thermal dissipation and more accurate output current passing through the LED.
- Significantly helps in reducing EMI
- Helping avoid overheating and damaging the TLC6C5912-Q1 IC.
- Overall cluster system can withstand start/stop, cold crank, and load dump conditions.

Tools & Resources

TIDA-00278
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